Zibo Seno Electronic Engineering Co., Ltd.



D20XB05-D20XB100



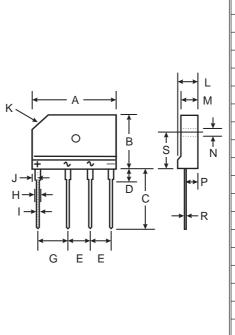
20A GLASS PASSIVATED BRIDGE RECTIFIER

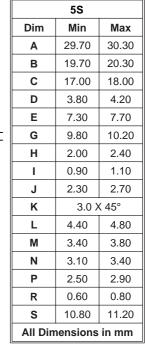
Features

- Glass Passivated Die Construction
- High Case Dielectric Strength of 1500V_{RMS}
- Low Reverse Leakage Current
- Surge Overload Rating to 240A Peak
- Ideal for Printed Circuit Board Applications
- Lead Free Finish/RoHS Complian

Mechanical Data

- Case: GBJ
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Plated Leads, Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Tin Finish).
- Polarity: Molded on Body
- Mounting: Through Hole for #6 Screw
- Mounting Torque: 5.0 in-lbs Maximum
- Marking: Type Number
- Weight: 6.6 grams (approximate)





Maximum Ratings and Electrical Characteristics @ T_A = 25°C unless otherwise specified

Single phase, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	D20XB 05	D20XB 10	D20XB 20	D20XB 40	D20XB 60	D20XB 80	D20XB 100	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} VR	50	100	200	400	600	800	1000	V
RMS Reverse Voltage	V _{R(RMS)}	35	70	140	280	420	560	700	V
Average Forward Rectified Output Current @ $T_C = 110^{\circ}C$	lo	20							А
Non-Repetitive Peak Forward Surge Current, 8.3 ms single half-sine-wave superimposed on rated load	I _{FSM}	240						А	
Forward Voltage per element @ I _F = 10A	VFM	1.05						V	
Peak Reverse Current@ $T_A = 25^{\circ}C$ at Rated DC Blocking Voltage@ $T_C = 125^{\circ}C$	I _R	10 500						μA	
I ² t Rating for Fusing (t < 8.3 ms) (Note 1)	l ² t	240						A ² s	
Typical Total Capacitance per Element (Note 2)	Ст	60						pF	
Typical Thermal Resistance Junction to Case (Note 3)	R _{0JC}	0.8						°C/W	
Operating and Storage Temperature Range	T _j , T _{STG}	-55 to +150						°C	

Notes: 1. Non-repetitive, for t > 1ms and < 8.3 ms.

2. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

3. Unit mounted on 300 x 300 x 1.6mm Cu plate heat sink.

4. RoHS revision 13.2.2003. Glass and High Temperature Solder Exemptions Applied, see EU Directive Annex Notes 5 and 7.

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Alldatasheet